

Customer View Model

3D_IGS.ZIP

English

Customer View Model

3D_STP.ZIP

English

Product Specifications

Engineering Report

Test Report For Cross Use Test, AMP 2.0mm HPI With JST PH

TIF

English

Test Report For Cross Use Test, AMP 2.0mm HPI With JST PH

PDF

English

Product Specification

Metric Interconnect System (Restricted To Sony Corporation)

PDF

English

AMP 2.0MM PITCH HPI WIRE-TO-BOARD SYSTEM.

PDF

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AMP 2.0mm Pitch HPI High Performance Interconnect (Low Cost) Wire-To-Board System

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AMP 2.0mm Pitch HPI High Performance Interconnect (Low Cost) Wire-To-Board System

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Qualification Test Report

AMP 2.0MM PITCH HPI WIRE-TO-BOARD SYSTEM.

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Product Environmental Compliance

TE Material Declaration

MD_440055-2_051920141044_dmtec

PDF

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Agency Approvals

CSA Certificate

VAL-U-LOK

PDF

English

FEATURES



Please review product documents or [contact us](#) for the latest agency approval information.

Please Note: Use the Product Drawing for all design activity.

Product Type Features

- Connector System** Wire-to-Board
- PCB Mounting Orientation** Right Angle
- Header Type** Partially Shrouded
- Sealable** No
- Connector & Contact Terminates To** Printed Circuit Board
- Product Type** Connector
- Connector Type** Header
- Connector Style** Plug
- Wire/Cable Type** Discrete Wire

Configuration Features

- Number of Positions** 2
- Number of Rows** 1
- Tail Orientation** Straight
- Backwall/Post Interruptions** Without

Electrical Characteristics

- Operating Voltage (VAC)** 250
- Operating Voltage (VDC)** 250

Body Features

- Post Plating Material** Tin
- Post Material** Brass

Contact Features

- Contact Shape** Square
- Contact Mating Area Plating Material** Tin
- Contact Current Rating (Max) (A)** 3
- Contact Style** Straight
- Contact Base Material** Brass
- Contact Plating Material** Tin
- Contact Termination Area Plating Material** Tin
- Contact Plating Material Finish** Bright
- Contact Type** Pin

Termination Features

- Termination Method to PC Board** Through Hole
- Contact Termination Type** Through Hole
- Termination Post Length** .134 in, 3.4 mm

Mechanical Attachment

- Contact Retention Type** Locking Lance
- PCB Mount Alignment** Without
- Mating Retention** Without
- PCB Mount Retention** With
- PCB Mount Retention Type** Kinked Tines
- Contact Retention** With

Housing Features

- Centerline (Pitch)** 2 mm [.079 in]
- Housing Material** Nylon 66 GF
- Housing Color** Natural

Dimensions

- Insulation Diameter** .9 mm [.0354 – .059 in]
- Height** 4.95 mm [.1949 in]
- Tail Length** 3.4 mm [.134 in]
- Width** 7.7 mm [.303 in]
- PCB Thickness (Recommended)** 1 – 1.6 mm [.039 – .063 in]
- Length** 6 mm [.236 in]
- Wire/Cable Size (AWG)** 30 – 24
- Mating Post Length** 3.5 mm [.138 in]

Usage Conditions

- Operating Temperature Range** -25 – 85 °C [-13 – 185 °F]

Operation/Application

- Pick and Place Cover** Without
- For Use With** 1735801-x

Industry Standards

- UL Flammability Rating** UL 94V-0

Packaging Features

- Packaging Method** Bag
- Packaging Quantity** 250

PRODUCT COMPLIANCE



Statement of Compliance

- Statement of Compliance**
- PDF